



















Detail Specification	
Platform	- CEB Form Factor: 12.0-in x 10.5-in; 30.5 cm x 26.7 cm - Premium Gold Capacitor design (100% Japan-made high-quality Conductive Polymer Capacitors)
	OC Formula Power Kit - Dig Power - Dusl-Stack MOSFET (DSM) - Multiplie Fitter Cap (MFC) (Fitter different noise by 3 different capacitors: DIP solid cap, POSCAP and MLCC) - Premium Alloy Choke (Reduce 70% core loss compare to iron powder choke) - 1
CPU	- Supports 3"and 2" Generation Intel [®] Core [™] 17/15/13 in LGA1155 Package - Supports Intel [®] Turbo Boost 2.0 Technology - Supports Intel [®] Meries unlocked CPU - Supports Hyer-Threading Technology
Chipset	- Intel® 277 - Supports Intel® Rapid Start Technology and Smart Connect Technology
Memory	- Dual Channel DDR3 memory technology 4.4 to DDR3 DIMM-clos. 5-upports DDR3 2000-(10C)/2800(10C)/2666(10C)/2400(10C)/2133(10C)/1866(10C)/1600/1333/1066 non-ECC, un-buffer ed memory. 4-Mar capacity of system memory: 3268 - Supports Intel [®] Extreme Memory Profile (XMP) 1.3 / 1.2
Expansion Slot	- 2x PCIExpress 3.0x16 slots POIEZ/PCIE4: single at x16 POIEZ) / x8 POIE4 or dual at x8/x8 mode) * POIE 3.0is only supported with Intel® Vp Bridge CPU. With Intel® Sandy Bridge CPU, it only supports POIE 2.0 1x PCIE repress 2.0x14 self POIE5: x4 mode) - 2x PCIExpress 2.0x14 self POIE5: x4 mode) - 2x PCIExpress 2.0x14 self POIE5: x4 mode) - 3x PCIExpress 2.0x14 self
Graphics	Intel® HD Graphics Built-in Visuals and the VGA outputs can be supported only with processors which are GPU integrated. Supports Intel® HD Graphics Built-in Visuals: Intel® Duick Sync Video 2.0, Intel® Infru™ 30, Intel® Clear Video HD Technology, Intel® Insider™, Intel® HD Graphics 2500/4000 Pixel Shader 50, DirectX11 with Intel® HD Brdge PUP, Ixels Shader 4.1, DirectX10.1 with Intel® Sandy Bridge CPL Mass, shared memory 176/IMB Supports HDMI. 4.3 Technology with max. resolution up to 1920x1200 @ 60Hz Supports Auto Lip Sync, Deep Color It2bpd., xVPCC and HBR IHigh Bit Rate Audio) with HDMI (Compliant HUM) monitor is required Supports HDDP function with HDMI port Supports HDDP function with HDMI port
Audio	- 7.1 CH HD Audio with Content Protection (Realtek ALC898 Audio Codec) - Premium Blu-ray audio support - Supports HK fruStudio**
LAN	- PCIE x1 Gigabit LAN 10/100/1000 Mb/s - Braidscm BCM57781 - Supports Make-On-LAN - Supports Energy Efficient Ethernet 802.3az - Supports Energy Efficient Ethernet 802.7az
Rear Panel I/0	/O Panel -1 x PS/Z Mouse/Keyboard Port -1 x DPS/Z Mouse/Keyboard Port -1 x DPM ST Court Port -1 x DPM ST Court Port -1 x DPM ST Court Port -2 x Ready-to-1 Use USS 20 Ports -3 x Ready-to-1 Use USS 20 Ports -1 x BJ-45 LAN Ports with LED IACD/LINK LED and SPEED LED) -1 x Clear CMOS Switch with LED -1 T x Clear CMOS Switch with LED -1 DAudio Jack-Rear Speaker / Central / Bass / Line in / Front Speaker / Microphone
	- 2 x SATA3 6.0 Gb/s connectors by Intel [®] Z77, support RAID [RAID 0, RAID 1, RAID 5, RAID 10, Intel Rapid Storage and Intel Smart Response Technology), NOQ, AHCl and "Hot Plug" functions -4 x SATA3 6.0 Gb/s connectors by Marvell SE9172, support RAID [RAID 0 and RAID 1], NOQ, AHCl and "Hot Plug" functions
USB 3.0	- 2 × Rear USB 3.0 ports by Intel® 277, support USB 1.0/2.0/3.0 up to 56b/s - 4 × Rear USB 3.0 ports by Erron EJ188H; support USB 10/2.0/3.0 up to 56b/s - 1 × From USB 3.0 header by Intel® 277 Eupports 2 USB 3.0 ports), supports USB 1.0/2.0/3.0 up to 56b/s
Connector	- 4 x SATA2 3.0 Gb/s connectors, support RAID (RAID 1, RAID 1, RAID 10, Intel Rapid Storage and Intel Smart Response Technology), NCQ, AHCI and Hot Plug functions - 6 x SATA2 6.0 Gb/s connectors - 1 x COR port based record of the state of
BIOS Feature	- 2 x 64Mb AMI UEF Legal BIOS with GUI support (1 x Main BIOS and 1 x Recovery Backup BIOS) - Supports "Plug and Play" - ACPI 11 Compliance Wake Up Events - SMBIOS 2.31 Support - CPU Core, IGPU, DRAM, 18V PLL, VTT, VCCSA Voltage Multi-adjustment
Support CD	- Drivers, Utiltiles, AntiVirus Software (Trial Version), CyberLink MediaEspresso 6.5 Trial, ASRock MAGIX Multimedia Suite - OEM
Unique Feature	- Formula Drive - ASRock Instant Boot

wer/MOS Temperature Sensing wer/MOS Fan Tachometer 'S Quiet Fan (Allows Chassis Fan Sp

POWER KIT /



12 + 4 Power Phase Design

ASRock Z77 OC Formula is designed with a 12 + 4 Power Phase design. It features sturdy components and completely smooth power delivery to the CPU. Plus, it offers unmatched overclocking capability and enhanced performance with the lowest temperature for advanced gamers as well.



Premium Alloy Choke

Compared to iron powder choke, the new PAC highlights a special alloy formula which is able to reduce up to 70% core loss. The revolutionary choke construction features a highly-magnetic and heat-resistant design, increasing the board's lifespan as well



(DSM) DSM is an innovative new desi

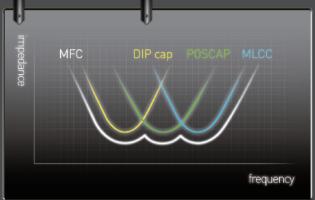
DSM is an innovative new design of MOSFETs. The silicon die area is increased by stacking two dies into a MOSFET. The larger the die area, the lower Rds(on). Compared to traditional discrete MOSFET, DSM can provide larger die area and lower Rds(on), so the power supply for CPU Vcore is more efficient.



Z77 OC Formula is equipped with CHIL 8328 silicon which features a new digital PWM (Pulse-Width Modulation) design, providing CPU Vcore voltage more efficiently and smoothly.



The ASRock MFC includes a combination of highly conductive MLCC, DIP cap and POSCAP. It helps the system filter noise from high-freq, mid-freq to low-freq noise, delivering enhanced and higher current to the CPU. With the combined power of three capacitors, MFC allows users to overclock their PC rig to extreme levels without worrying about the hardware components.



COOLING KIT



Twin-Power Cooling combines active air cooling with water cooling. The ultimate heatpipe cooling design maximizes the system's convection to expel hot air out, providing great air flow and faster heat dissipation.



ASRock Z77 OC Formula is built on an 8-layer-PCB design. It comes with 4 sets of 2 ounces copper inner layers, using only carefully selected copper materials for PCB layers, delivering lower temperature and higher energy efficiency for overclocking.



GELID GC-Extreme Thermal Compound is an added bonus that allows overclockers to stabilize the CPU's temperature.

CONNECTOR KIT



Hi-Density Power Connector

Hi-Density Power Connector features a solid square-pin design. ASRock Z77 OC Formula is equipped with High-Density Power Connector for the CPU power connector. The optimized design can reduce 23% power loss and decrease connector temperature up to 22°C.



ASRock has embedded 15 μ Gold Finger for both CPU sockets and DRAM slots. Compared to other boards that come with only 3-4 μ , ASRock Z77 OC Formula provides 15 μ gold components within the sockets, delivering triple performance than usual.



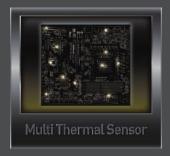
a chance to learn a few tricks matter whether you're using a K-Series or No-K Series CPU, NickShih's OC Profile will automatically detect your CPU and offer you different levels of overclocking.



blend of system configuration stunning visuals. The unprecedented UEFI provides a



all-in-one software to fine-tune FAN-tastic Tuning, Overclocking, OC DNA, IES,



Multi Thermal Sensor provides users the temperature of mother board graphically in ASRock UEFI Setup Utility and Formula Drive, so that users may precisely keep track and control of the temperature of each parts of their motherboard



(RPM) relative to the system temperature. Users are able to adjust the setting by clicking the "+/-" and confirm by "APPLY" afterwards.



raise and lower the CPU ratio, voltage. OC enthusiasts can use it to find their CPU's best margin.



to remove then reinstall their PCIe cards back into the PCIe slots and fear of damaging the motherboard and its components, ASRock has added enable or disable the PCIe slots in a flick of your finger.



new collection of voltage fine tuning options in ASRock UEFI Setup Utility. It provides more than enough voltage configuration options for



Formula. It allows overclockers to easily and quickly get the



with an abundant collection of subtle DRAM settings for professional tweaking. It is an independent application of that runs under Windows® OS and your changes will take effect



Technology (XFast RAM, XFast LAN, and XFast USB) allows system performance, LAN speed and USB transfer speed.



Brilliantly designed for gaming, Virtu Universal MVP™ switchable graphics software assigns tasks dynamically to the features two exciting techniques – HyperFormance™ and Virtual